



DB201S THRU DB207S

Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case:DB-S, molded plastic
- Terminals: plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting position: Any
- Marking: type number
- Lead Free: For RoHS / Lead Free Version

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.
 Single Phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	DB201S	DB202S	DB203S	DB204S	DB205S	DB206S	DB207S	UNITS
Peak Repetitive Reverse Voltage	V_{RRM}								
Working Peak Reverse Voltage	V_{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V_{DC}								
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@ $T_C=100^\circ C$	IF(AV)	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60							A
I^2t Rating for Fusing ($t < 8.3ms$)	I^2t	14.94							A ² s
Forward Voltage per element @IF=2.0A	V_{FM}	1.0							V
Peak Reverse Current @ $T_A=25^\circ C$ At Rated DC Blocking Voltage @ $T_A=125^\circ C$	I_R	5.0 200							uA
Typical Junction Capacitance per leg (Note 2)	C_J	25							pF
Typical Thermal Resistance per leg	$R_{\theta JA}$	40							°C/W
	$R_{\theta JL}$	15							
Operating and Storage Temperature Range	T_J, T_{STG}	-55to+150							°C

Note:1. Mounted on glass epoxy PC board with 1.3mm² solder pad.
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

2.0 A Sin le-Phase Glass Passivated Bridge Rectifiers
 Rectifier Reverse Voltage
 50 to 1000V

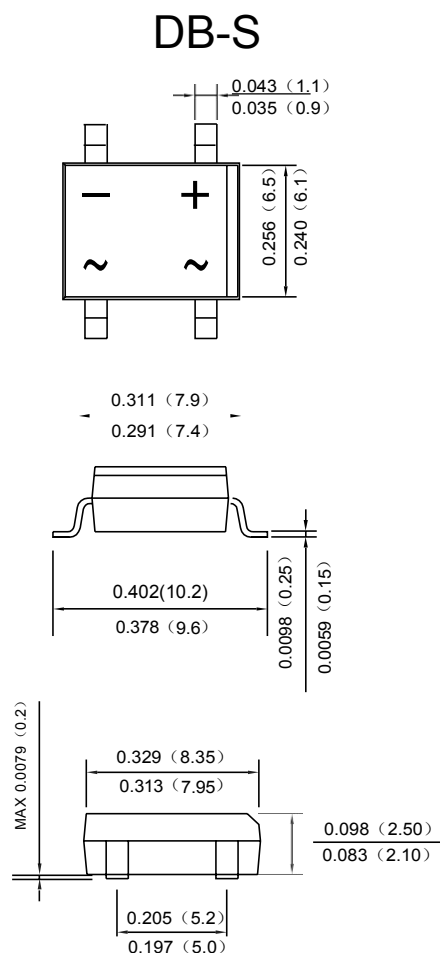




Fig. 1 Output Current Derating Curve

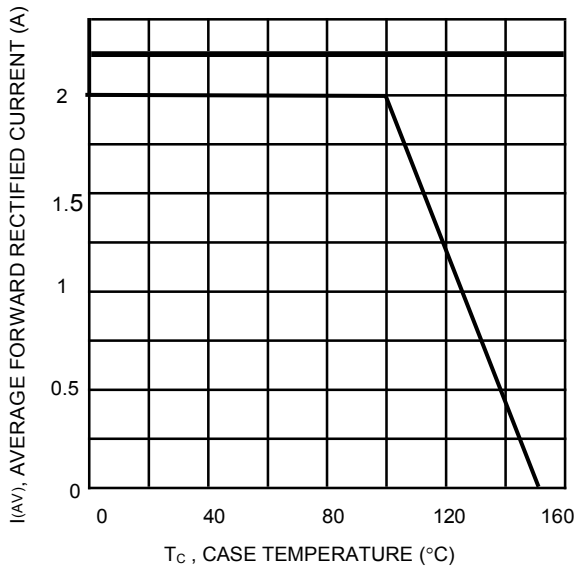


Fig. 2 Typical Forward Characteristics (per leg)

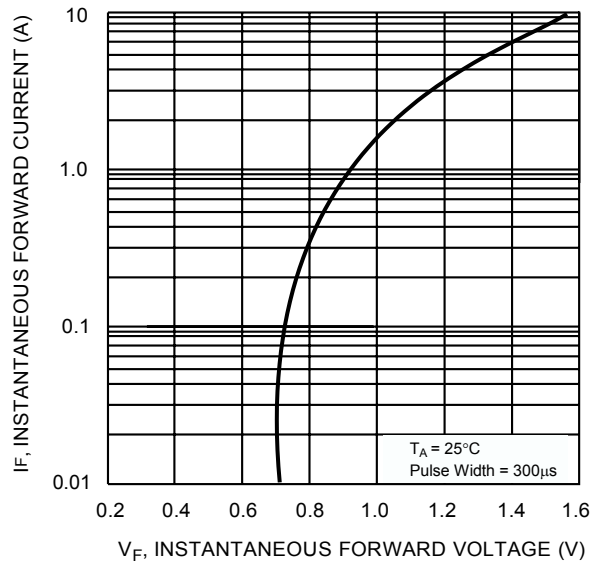


Fig. 3 Maximum Peak Forward Surge Current (per leg)

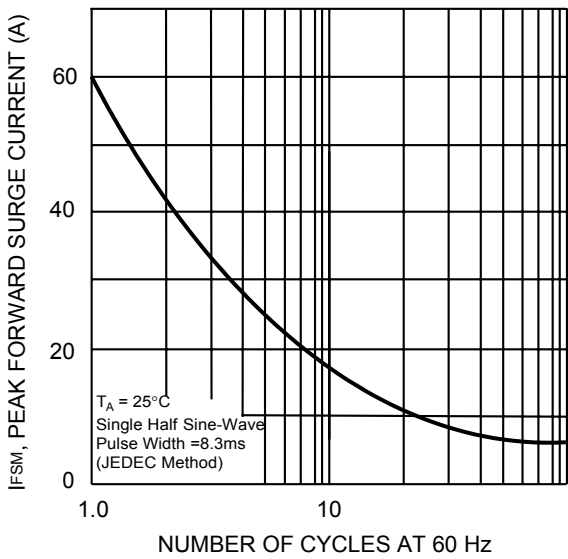


Fig. 4 Typical Reverse Characteristics (per element)

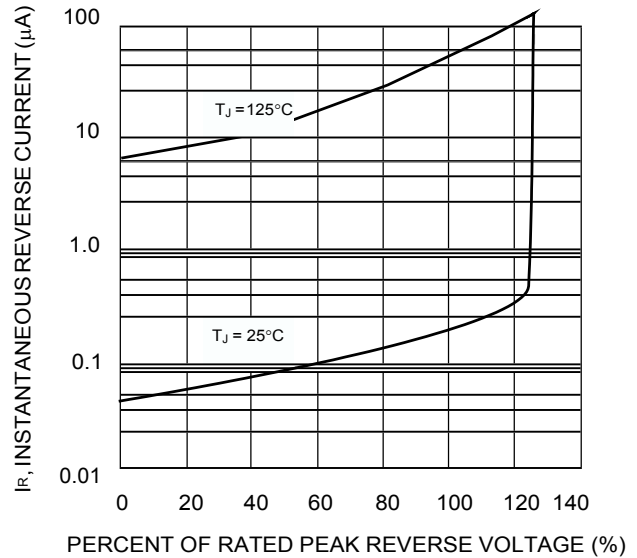
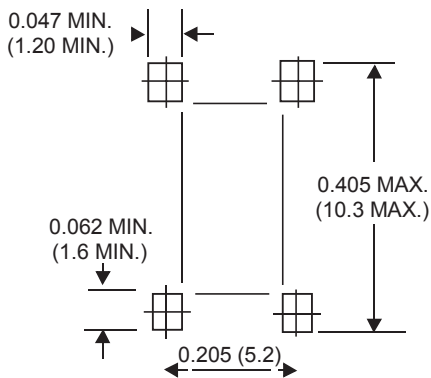


Fig. 5 Mounting Pad Layout





注意事项

1. 深圳市华天微电子有限公司的产品销售分为直销和销售代理，无论哪种方式，订货时请与公司核实。
2. 购买时请认清公司商标，如有疑问请与公司本部联系。
3. 在电路设计时请不要超过器件的绝对最大额定值，否则会影响整机的可靠性。
4. 本说明书如有版本变更不另外告知

NOTE

1. Shenzhen Huatianwei Electronics co., Ltd sales its product either through direct sales or sales agent , thus, for customers, when ordering , please check with our company.
2. We strongly recommend customers check carefully on the trademark when buying our product, if there is any question, please don't be hesitate to contact us.
3. Please do not exceed the absolute maximum ratings of the device when circuit designing.
4. Shenzhen Huatianwei Electronics co., Ltd reserves the right to make changes in this specification sheet and is subject to change without prior notice.

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